

2SD1845

Silicon NPN Triple-Diffused Planar Type

Horizontal Deflection Output

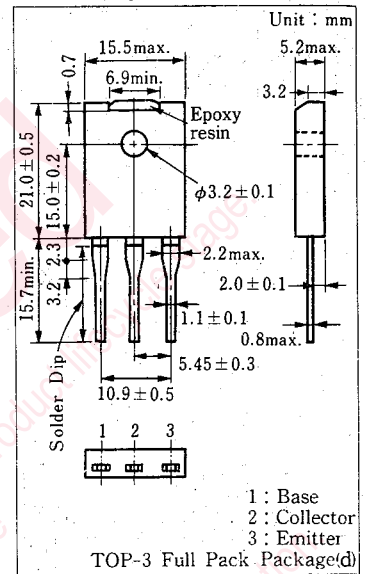
■ Features

- Damper diode built-in
- Minimizes external component counts and simplifies circuitry
- High breakdown voltage, high reliability
- High speed switching
- Wide area of safety operation (ASO)
- "Full Pack" package for simplified mounting on a heat sink with one screw

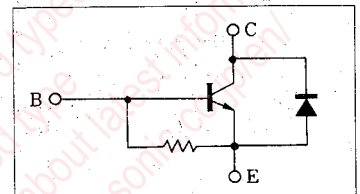
■ Absolute Maximum Ratings (Tc=25°C)

Item	Symbol	Value	Unit	
Collector-base voltage	V _{CBO}	1500	V	
Collector-emitter voltage	V _{CES}	1500	V	
	V _{CEO}	700	V	
Emitter-base voltage	V _{EBO}	7	V	
Peak collector current	I _{CP}	7	A	
Collector current	I _C	2.5	A	
Base current	I _B	1.5	A	
Collector power dissipation	P _C	T _C = 25°C	60	W
		T _a = 25°C	3	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 ~ +150	°C	

■ Package Dimensions

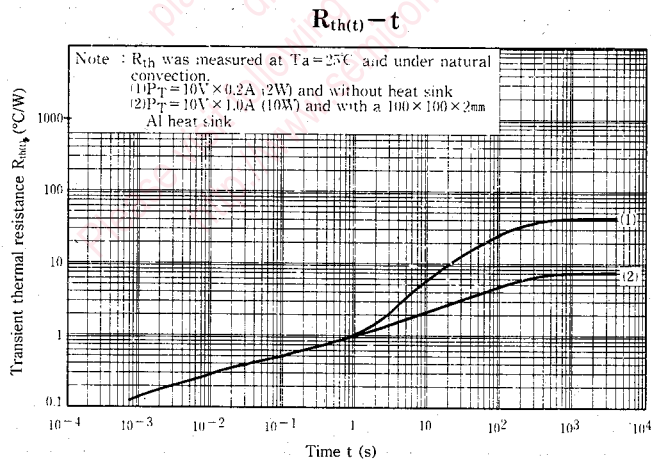
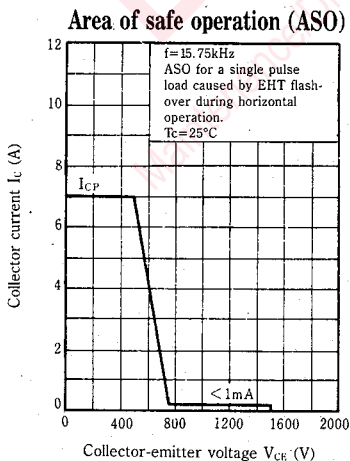
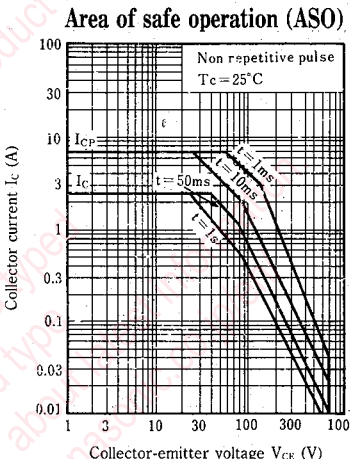
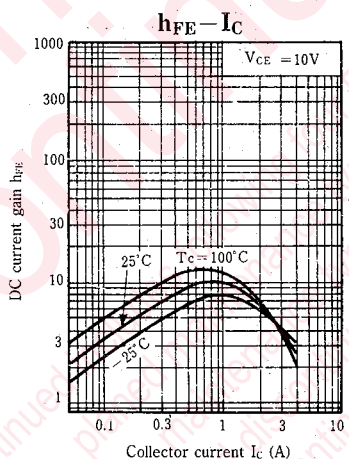
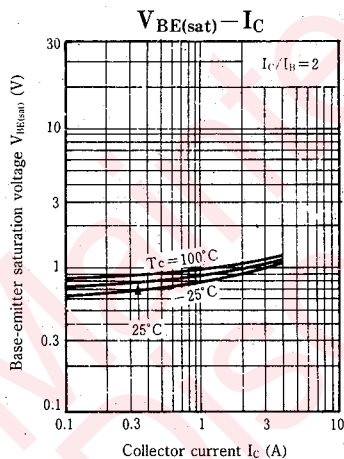
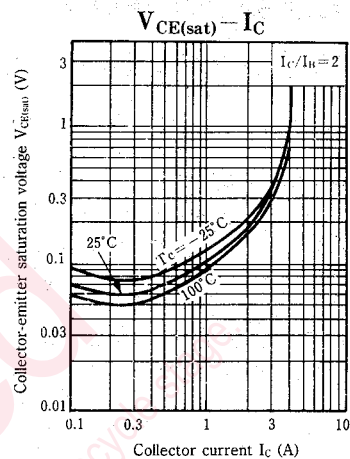
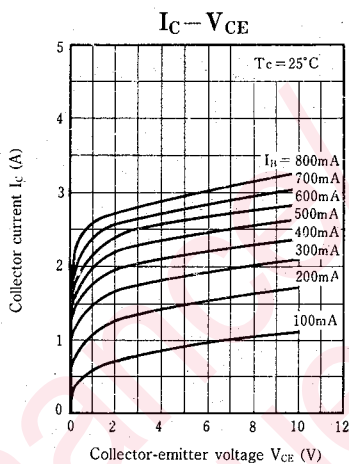
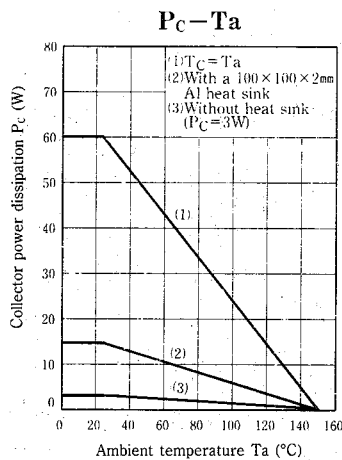


■ Inner Circuit



■ Electrical Characteristics (Tc=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Collector cutoff current	I _{CBO}	V _{CB} = 750V, I _E = 0			10	μA
		V _{CB} = 1500V, I _E = 0			1	mA
Emitter-base voltage	V _{EBO}	I _F = 500mA, I _C = 0	7			V
DC current gain	h _{FE}	V _{CE} = 5V, I _C = 0.5A		5	25	
		V _{CE} = 10V, I _C = 2A	3.5			
Collector-emitter saturation voltage	V _{CE(sat)}	I _C = 2A, I _B = 0.6A			8	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C = 2A, I _B = 0.6A			1.5	V
Transition frequency	f _T	V _{CE} = 10V, I _C = 0.5A, f = 0.5MHz		2		MHz
Storage time (L load)	t _{stg}	I _C = 2A, I _{B1} = 0.6A			7	μs
Collector current fall time (L load)	t _f	I _{B2} = -0.6A, L _{leak} = 5μH			0.8	μs
Storage time (R load)	t _{stg}	I _C = 2A, I _{B1} = 0.6A		1.5		μs
Collector current fall time (R load)	t _f	I _{B2} = -1.2A, V _{CC} = 200V		0.2		μs
Diode forward voltage	V _F	I _C = -2.5A, I _B = 0			2	V



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